2SA844

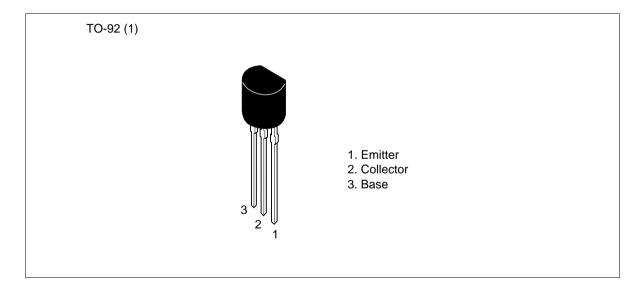
Silicon PNP Epitaxial

HITACHI

Application

Low frequency amplifier

Outline





2SA844

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	– 55	V
Collector to emitter voltage	V _{CEO}	– 55	V
Emitter to base voltage	V_{EBO}	– 5	V
Collector current	I _c	-100	mA
Emitter current	I _E	100	mA
Collector power dissipation	P _c	300	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Electrical Characteristics ($Ta = 25^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	- 55	_	_	V	$I_{c} = -10 \mu A, I_{e} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	- 55	_	_	V	$I_{c} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	- 5	_	_	V	$I_{E} = -10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-100	nA	$V_{CB} = -18 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	-50	nA	$V_{EB} = -2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	160	_	800		$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	-0.1	-0.5	V	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$
Base to emitter voltage	V_{BE}	_	-0.66	-0.75	V	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Gain bandwidth product	f _T	_	200	_	MHz	$V_{CE} = -12 \text{ V}, I_{E} = -2 \text{ mA}$
Collector output capacitance	Cob	_	2.0	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

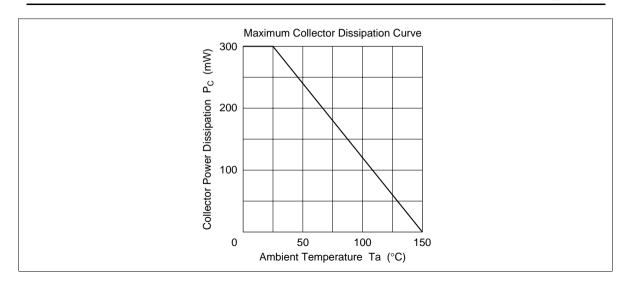
Note: 1. The 2SA844 is grouped by h_{FE} as follows.

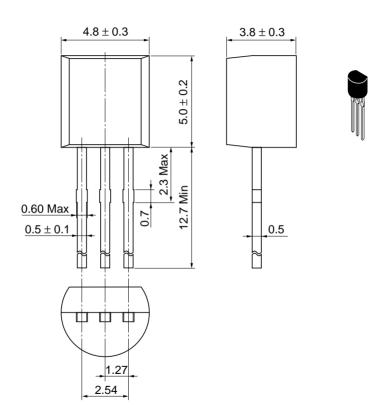
С	D	E
160 to 320	250 to 500	400 to 800

See characteristic curves of 2SA836.

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2SA844





Hitachi Code	TO-92 (1)
JEDEC	Conforms
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Weight (reference value)	w 0.25@lectronica.com

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